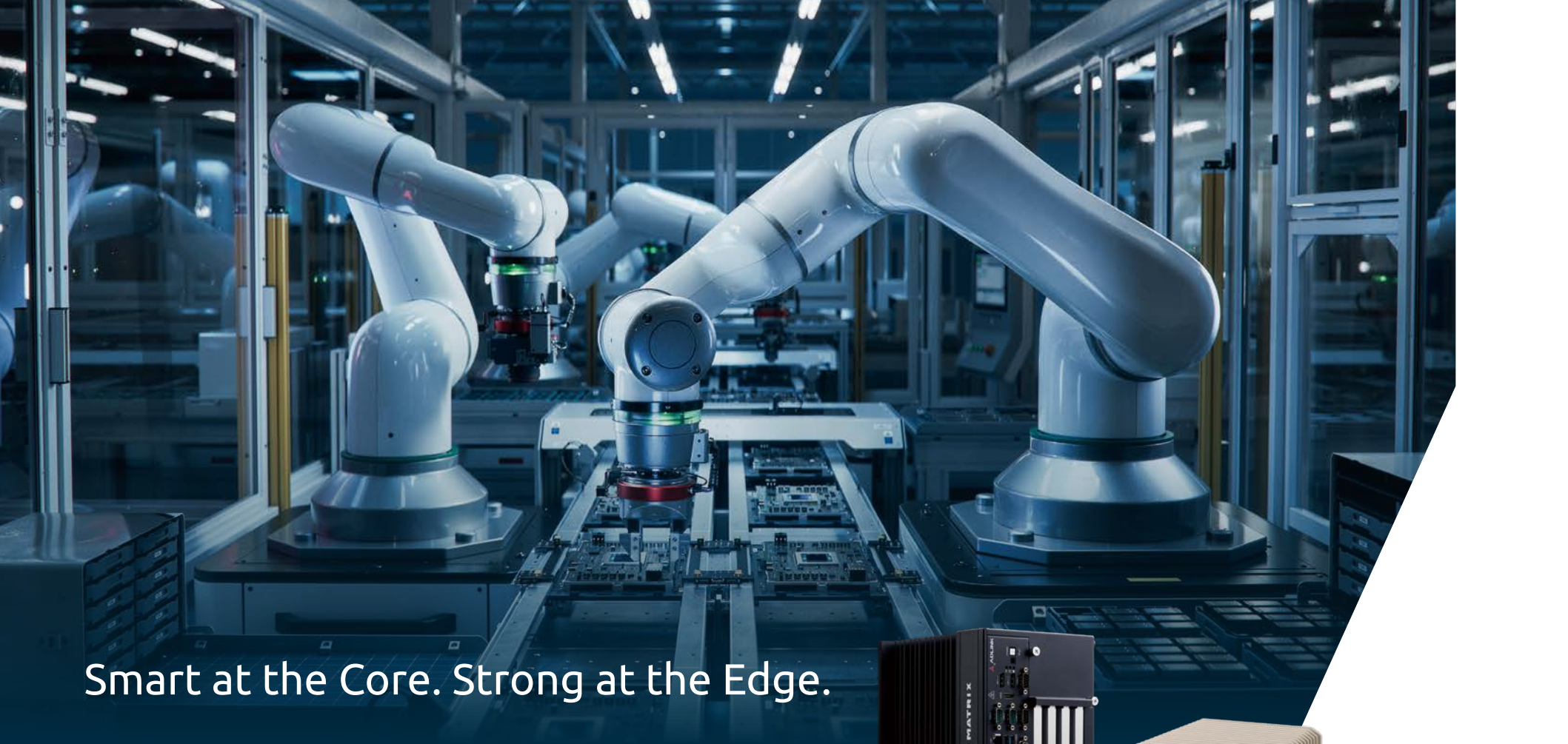




Smart at the Core. Strong at the Edge.

ADLINK Embedded Computing Solutions





/// Compact Series

Palm-sized for space-limited environments



/// Integrated Series

Balanced size-to-performance ratio



/// Expandable Series

Up to 4 expansion slots for peak performance

Shaping the Future with Matrix Embedded Computers

Harsh industrial and urban environments demand edge computing solutions that won't fail under pressure. ADLINK's Matrix embedded platforms are purpose-built to address these challenges, ensuring rugged durability, real-time processing, and seamless integration across diverse applications. Paired with ADLINK's edge software services such as BIOS customization, OS image management, and edge sensing APIs, Matrix is uniquely equipped to simplify development and accelerate deployment. There is a Matrix for every need. With three distinct lines, each optimally tailored for size, performance, and expansion, Matrix brings powerful computing straight to the edge.

Built on Experience. Engineered for the Edge.

With decades of embedded design experience, ADLINK's Matrix series is expertly built for reliable performance in the field. These rugged edge platforms are designed to operate in challenging environments and deliver the durability, stability, and uptime that mission-critical systems require. Every detail, from thermal design to component integration, reflects technical insight and experience. The result is a resilient, future-ready solution that keeps pace with evolving requirements without compromising reliability.



Versatile Platform Options

- Featuring Intel®, Core™, and Atom® processors
- Integrated NVIDIA Ampere GPUs
- Multiple form factors



Flexible I/O and Expansion

- Application-specific connectors
- Add-on expansion slots



Resilient Engineering

- -20 - 60°C fanless operating temperature
- Shock and vibration resistant
- Stainless steel enclosure, corrosion-resistant



Application Focused Design

- Customizable I/O via AFM
- Modular motion, vision, and frame grabber cards
- Industrial-grade cameras and peripheral



High Bandwidth RF Connectivity

- High-speed data with low-latency transmission
- 4G & 5G WWAN
- Wi-Fi 6E (802.11ax) WLAN



Remote Edge Management with EdgeGO

- Real-time device monitoring and control
- Secure OTA updates for seamless software deployment
- Remote diagnostics and troubleshooting
- Scalable management for large device networks

Build your system your way with Adaptive Function Modules

When standard systems hit their limits, Adaptive Function Modules unlock a new level of design freedom. Built on Matrix's unique modular architecture, AFMs allow application-specific expansion from a wide selection of connectors, circuits, slots, and I/O options. This flexibility transforms a fixed platform into a tailored solution without added complexity.

AFM



Integrated Circuit



Add-on Expansion Slots



Std. Industrial I/O Ports





Simplifying System Configuration & Maintenance with Flexible Modularity

QuickSet is ADLINK's signature modular design feature. It enables industrial users to build, configure, and scale with confidence. From creating a new system to upgrading an existing one, its intuitive setup delivers tool-free, plug-and-play access to CPU, memory, and storage. Built on the Matrix product line's rugged architecture, QuickSet is proven to reduce deployment time and streamline field maintenance.

Lift



Swap

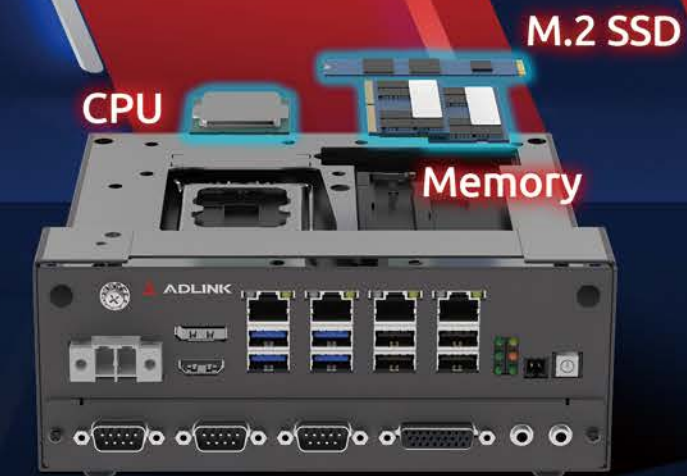


GO

*Lift top cover with
only 8 screws*



*Easy maintenance &
reconfigurations for
any setup*



*Field-ready in
minutes*



Applications

Smart Manufacturing

Public Safety

Oil & Gas

Transportation

Maritime

Smart Manufacturing

Challenges & Requirements

- Integration complexity makes it difficult to add I/O or motion control to existing systems
- Environmental sensitivity challenges stable performance in extreme conditions without constant monitoring

Solution & Insight

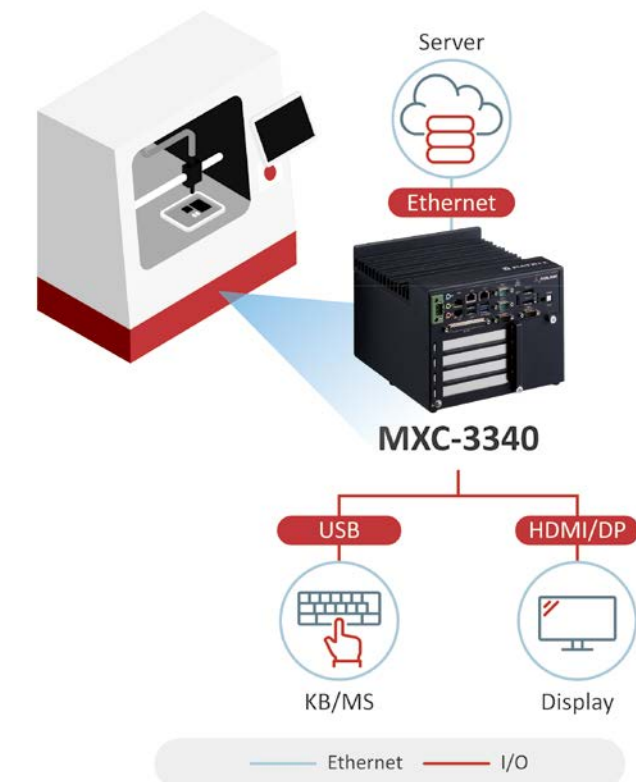
- MXC-3340 ensures stable communication with isolated RS232/485 and DIO for harsh environments
- Low power design helps reduce energy consumption and operating costs
- Three PCIe slots enable easy expansion for DIO and motion control

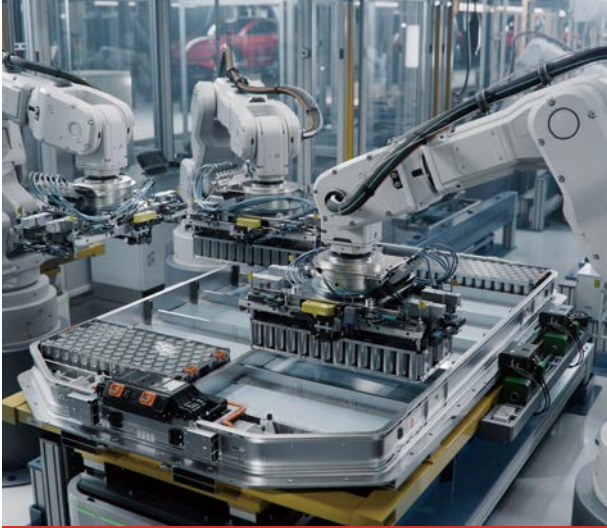
Use Case

Production Monitoring

Overview

In modern production environments, stable performance and continuous visibility are essential for keeping operations on track. However, expanding existing systems with additional I/O or motion control often introduces complexity, while harsh conditions can undermine reliable performance. The MXC-3340 is engineered to overcome these barriers with stable industrial communication, energy-efficient operation, and flexible expansion options. By combining rugged reliability with adaptable design, it provides a future-ready platform that keeps production lines efficient, resilient, and easy to manage.





Smart Manufacturing

Challenges & Requirements

- Hard to find compact systems that support complex motion in tight spaces
- Sub-500 μ s EtherCAT cycle times for 8-axis control demand advanced integration

Solution & Insight

- MXE-230 delivers powerful motion control in a compact form factor
- Achieves 250 μ s cycle time with SuperCAT for fast, precise motor control
- Offers LAN expansion via AFM and M.2 for flexible robotic connectivity

Use Case

Motor Driver Controller

Overview

Industrial robots demand precise, responsive motion, especially when operating in compact environments where every millimeter counts. However, achieving high-speed, multi-axis control in such a limited space introduces both performance and integration challenges. The MXE-230 delivers powerful motion control in a small footprint, ensuring fast cycle times and reliable accuracy. With the flexibility to expand connectivity as systems evolve, it provides a future-ready solution that keeps robotic operations smooth, efficient, and adaptable.



Smart Manufacturing

Challenges & Requirements

- Requires high-speed data collection across devices
- Must support multiple PLC brands and fit into compact cabinets
- Needs efficient monitoring to minimize system downtime

Solution & Insight

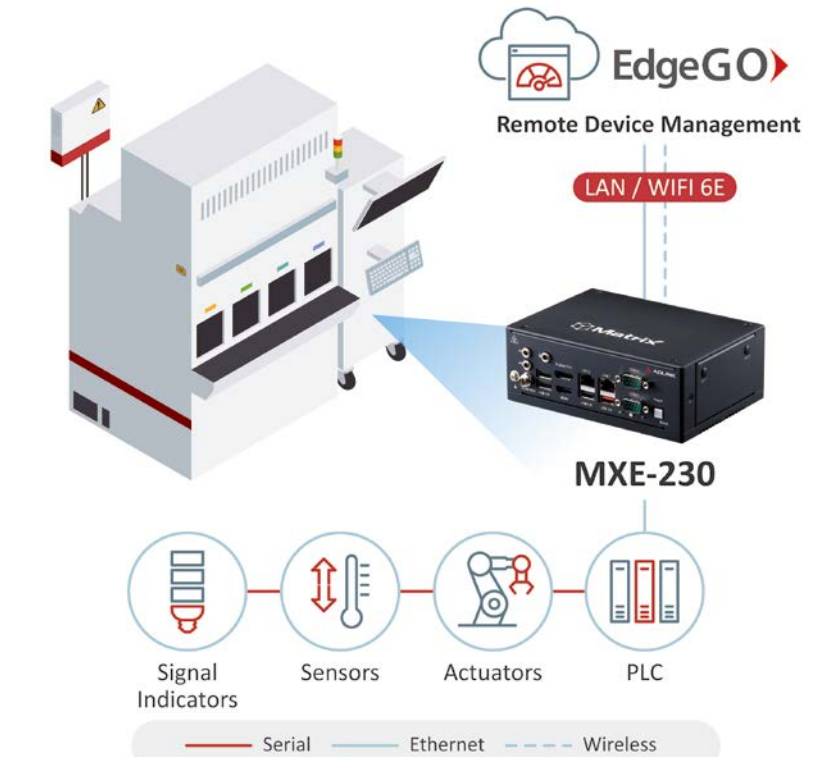
- MXE-230 collects data from multiple PLCs within a 10 ms cycle
- EdgeGO enables remote monitoring and control to reduce downtime
- Fanless and wide-temp design ensures reliable, rugged operation
- Supports seamless integration with various PLC brands and protocols

Use Case

Data Acquisition Through PLC

Overview

Factories rely on real-time insight from PLC systems to keep processes accurate, efficient, and continuously running. Yet collecting high-speed data across different brands and fitting everything into compact control cabinets can be a major challenge. The MXE-230 solves this by delivering fast, reliable PLC data acquisition with cycle times as short as 10 ms, while EdgeGO enables remote monitoring to minimize downtime. With a rugged, fanless design and broad protocol support, it ensures smooth integration and dependable performance in demanding industrial environments.





Smart Manufacturing

Challenges & Requirements

- Integration with existing systems is time-consuming and complex
- Frequent maintenance increases operational costs in harsh environments

Solution & Insight

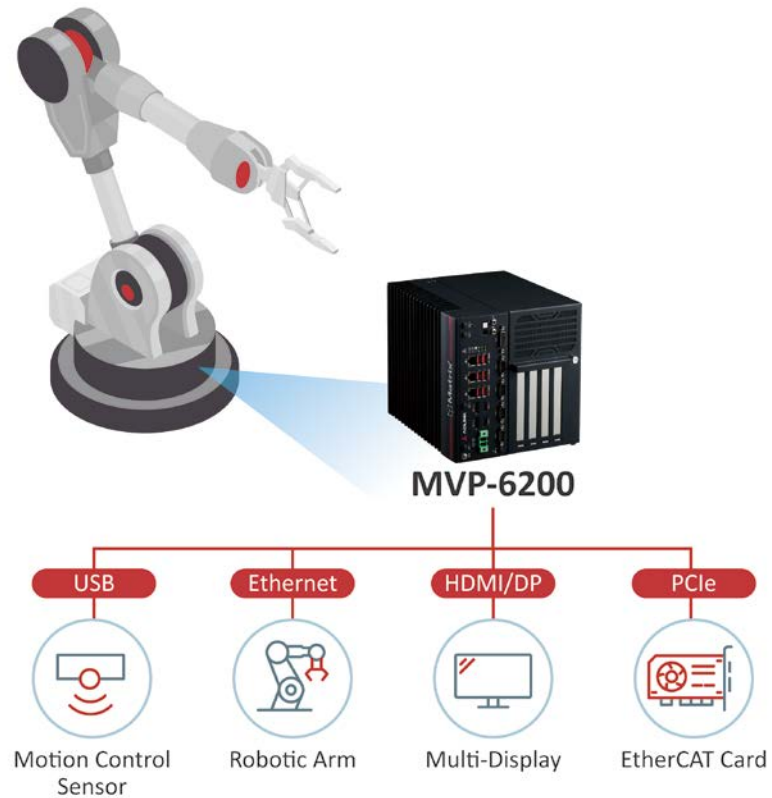
- MVP-6200 supports 16x DI and 16x DO with 2.5 kV isolation for reliable I/O protection
- Includes M.2 2280 for SSD with SED support and optional M.2 2230 for Wi-Fi
- Features latch switch power button with configurable S0 and S5 behaviour
- Customizable chassis allows pre-installation of fieldbus control board using consigned parts

Use Case

Industrial Robotic Machines

Overview

Robotic systems play a central role in automating complex industrial tasks, where stable I/O control and smooth integration are critical for consistent performance. Yet connecting robots to existing systems can be time-consuming, while frequent maintenance in harsh environments raises costs and risks downtime. The MVP-6200 addresses these needs with high-isolation I/O for reliable operation, customizable expansion for fieldbus integration, and flexible storage and connectivity options. This compact platform simplifies deployment and ensures dependable performance across demanding robotic applications.



Public & Safety

Challenges & Requirements

- Operates 24/7 in compact, high-security environments
- Complex integration with legacy border control systems and real-time document analysis

Solution & Insight

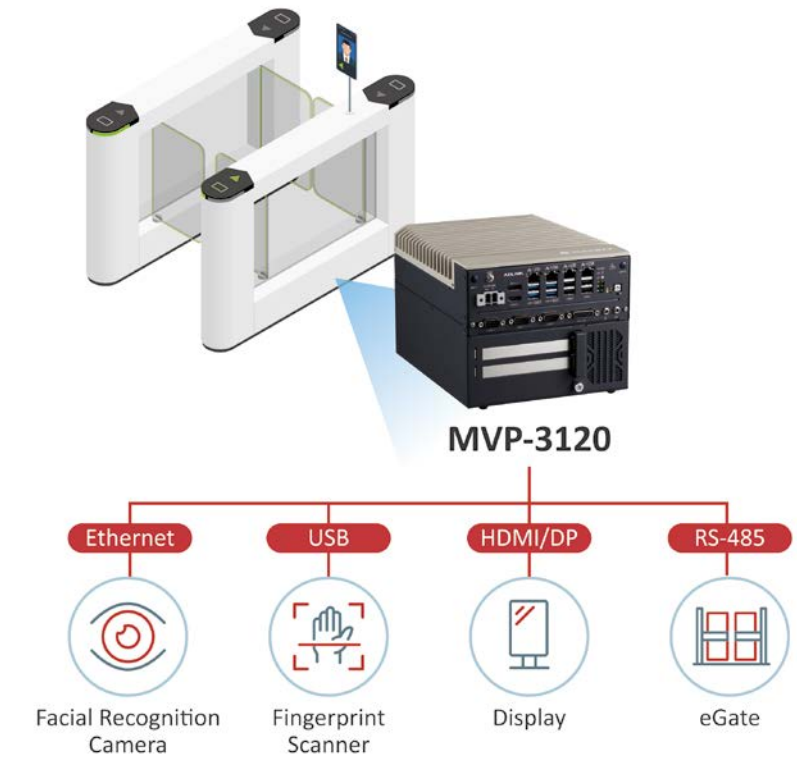
- MVP-3120 improves inspection speed with dual monitor support and real-time analysis
- Fanless, GPU-ready design ensures quiet, efficient operation
- Durable and dust-resistant for reliable performance in harsh conditions with low maintenance

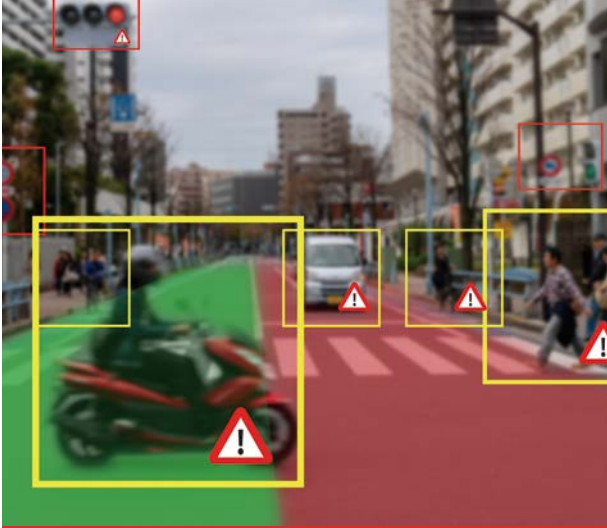
Use Case

Inspection System for Border Control

Overview

Border control operations demand constant accuracy and efficiency to verify documents in high-security environments. These systems must run continuously in compact spaces while handling complex integration with legacy infrastructure and real-time analysis requirements. The MVP-3120 meets these challenges with dual monitor support for streamlined inspections, automated document scanning for faster throughput, and a fanless, GPU-ready design that ensures durable, low-maintenance operation. Built for reliability, it keeps border checkpoints efficient and secure under demanding conditions.





Public & Safety

Challenges & Requirements

- Accurate object detection with limited processing power
- AI deployment in compact spaces like parking meters or traffic cabinets
- Seamless integration into existing systems without major changes

Solution & Insight

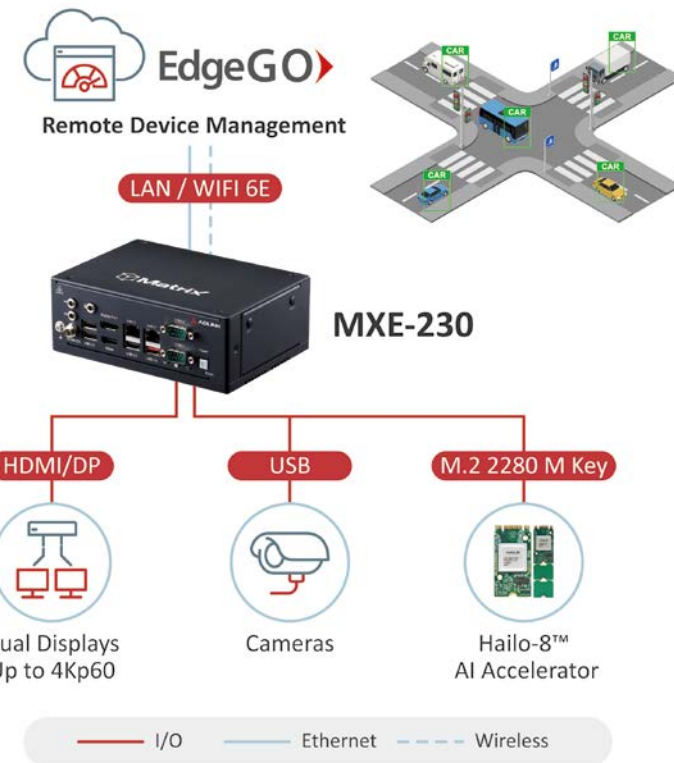
- The MXE-230 is powered by Intel® N97 for balanced performance with only 12W power draw
- Compact 1.2L fanless design fits easily into tight spaces
- Supports 26 TOPS AI performance with Hailo-8 via M.2 for efficient AI integration

Use Case

AI Object Detection

Overview

Cities and industries are turning to AI object detection to improve safety, efficiency, and automation in daily operations, from traffic monitoring to facility security. Yet deploying AI in the field often means working with limited space, restricted power budgets, and the need for seamless integration into existing infrastructure. The MXE-230 makes this possible with a compact, fanless design that fits easily into confined environments and efficient processing that supports real-time analysis. Combined with scalable AI acceleration, it enables accurate detection and faster response in a practical, deployable form.



Oil & Gas

Challenges & Requirements

- Reliable operation in dusty, sandy, and harsh environments
- 24/7 performance required in remote, rugged locations

Solution & Insight

- MVP-5200 supports 6x 2.5GbE LAN for fast, stable data transmission
- Fanless, compact system with Intel CPU ensures efficient, reliable performance
- Rugged, maintenance-free design built for harsh environments

Use Case

Production Monitoring

Overview

Land-based drilling sites require centralized control to ensure safe, efficient, and cost-effective operations under challenging environmental conditions. Dust, sand, and high heat make it difficult to maintain stable performance while ensuring continuous monitoring of equipment and resources. The MVP-5200 provides the reliability these sites need, with high-speed LAN for real-time data transmission, a compact, fanless design for maintenance-free operation, and rugged durability built to withstand harsh onshore environments. This ensures consistent performance and reduced downtime across critical drilling operations.





Transportation

Challenges & Requirements

- System stability for minimal downtime
- Durability and environmental resistance
- System integration and maintenance challenges

Solution & Insight

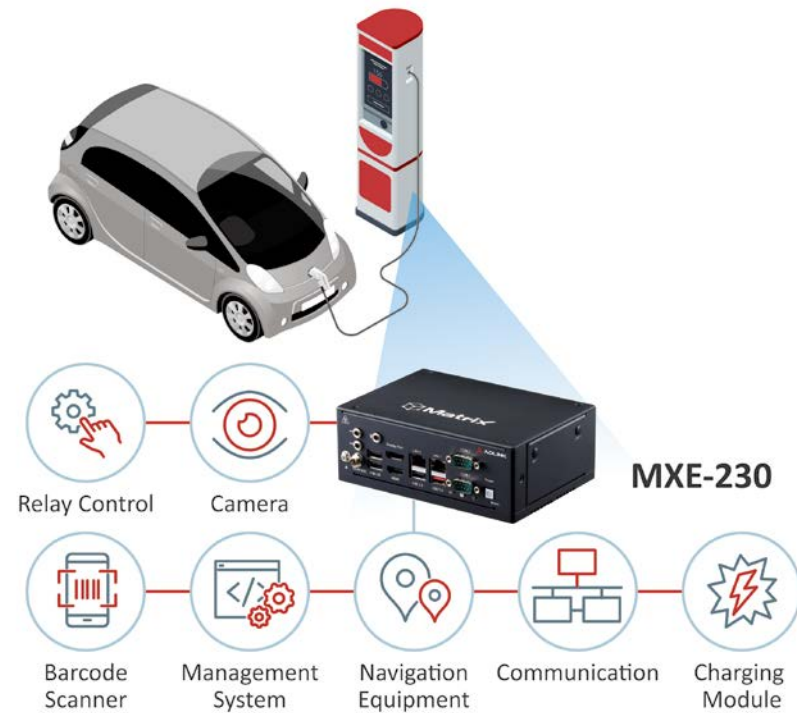
- MXE-230 has a fanless aluminium enclosure that withstands heat, humidity, and dust
- Empowers edge computing and remote management for real-time insights and uptime
- AWS-certified for seamless cloud integration and scalable IoT deployment

Use Case

EV Charging

Overview

As EV infrastructure scales, operators face growing demands for system stability, durability, and ease of integration to ensure minimal downtime. The MXE-230 addresses these challenges with a fanless aluminium enclosure built for outdoor environments, ensuring long-term performance stability. Empowered with edge computing and remote management, it delivers real-time insights and predictive maintenance for optimal uptime. AWS certification enables effortless cloud integration and scalable IoT management across distributed charging networks.



Transportation

Challenges & Requirements

- SSD replacements need careful handling and can disrupt operations
- Diverse I/O interfaces may lead to compatibility issues and added setup effort

Solution & Insight

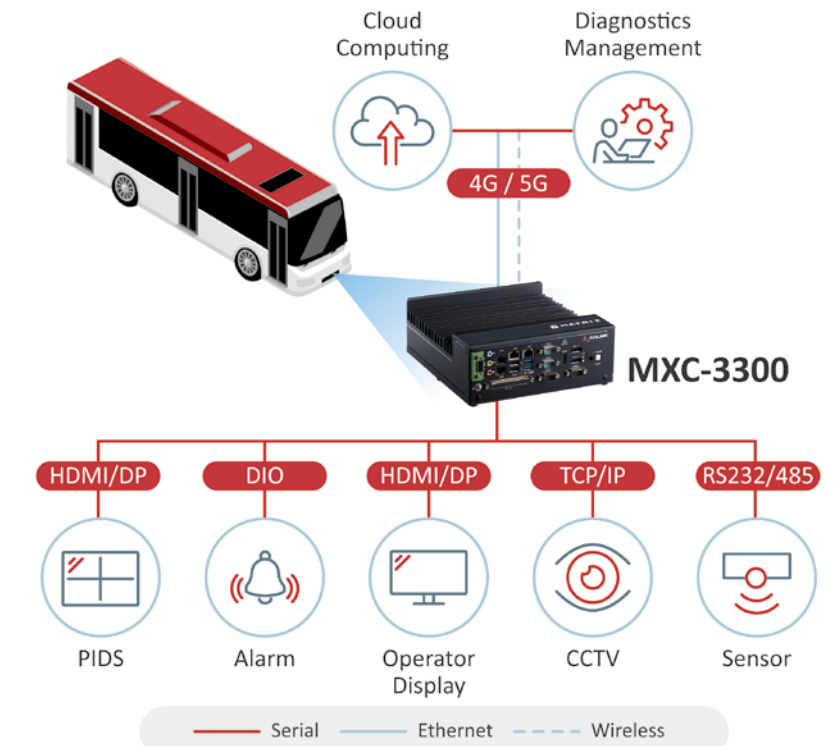
- MXC-6200 features a removable SSD tray for easy maintenance
- Multiple I/O interfaces ensure seamless device integration
- Supports 9–36V input for flexible, stable power across applications

Use Case

Intelligent eBus Management

Overview

Public transit systems are adopting eBuses to provide more eco-friendly and efficient transportation while cutting costs and easing urban congestion. Managing these vehicles, however, requires reliable systems that can handle frequent maintenance and connect with a wide range of devices without disrupting daily operations. The MXC-6200 provides a practical solution with a removable SSD tray for simplified servicing, versatile I/O support for smooth integration, and wide-range power input to ensure stable performance on the road. This enables eBus fleets to stay dependable, efficient, and easier to maintain.





Maritime

Challenges & Requirements

- Meeting multiple marine certifications adds design complexity
- Integrating with legacy vessel systems increases setup time and cost

Solution & Insight

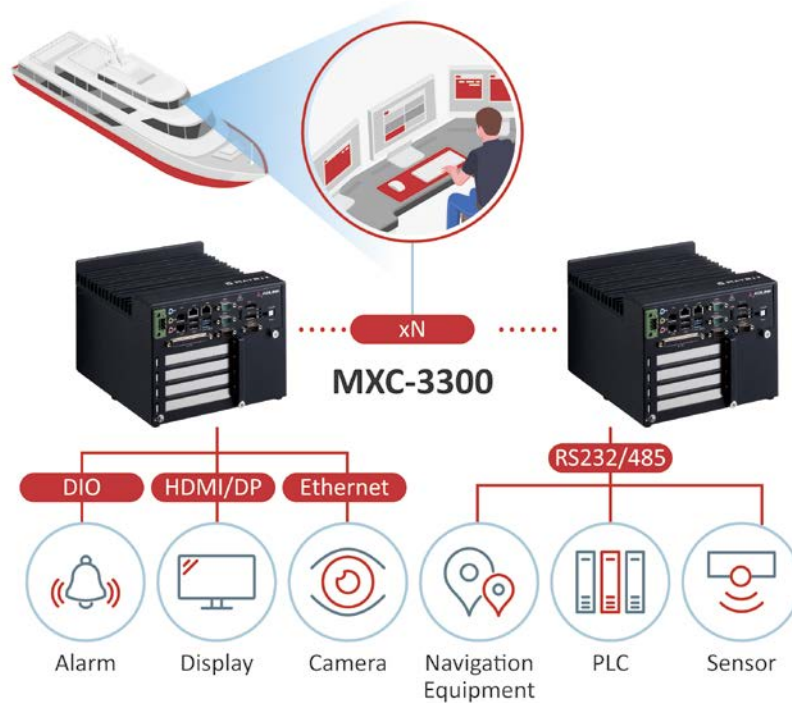
- Marine-certified with DC module and compliant design, including: IEC 60945, IACS E10, and DNVGL-CG-0339
- Isolated RS232/485 and DIO provide stable, high-performance communication in harsh conditions

Use Case

Marine Control Room System

Overview

Vessel control rooms are the backbone of maritime operations, responsible for safe navigation and reliable communication around the clock. In these environments, systems must not only withstand vibration, humidity, and electrical interference but also comply with strict international standards. The MXC-3340 is purpose-built to meet these demands, combining a certified design with stable, isolated communication interfaces. Ensuring dependable performance in harsh maritime conditions enables efficient vessel management and reduces integration challenges across both new and legacy ship systems.



Maritime

Challenges & Requirements

- Processing multiple data sources like ECDIS, radar, and GPS strains system performance
- Dual PCIe slot integration may require complex configuration for navigation systems

Solution & Insight

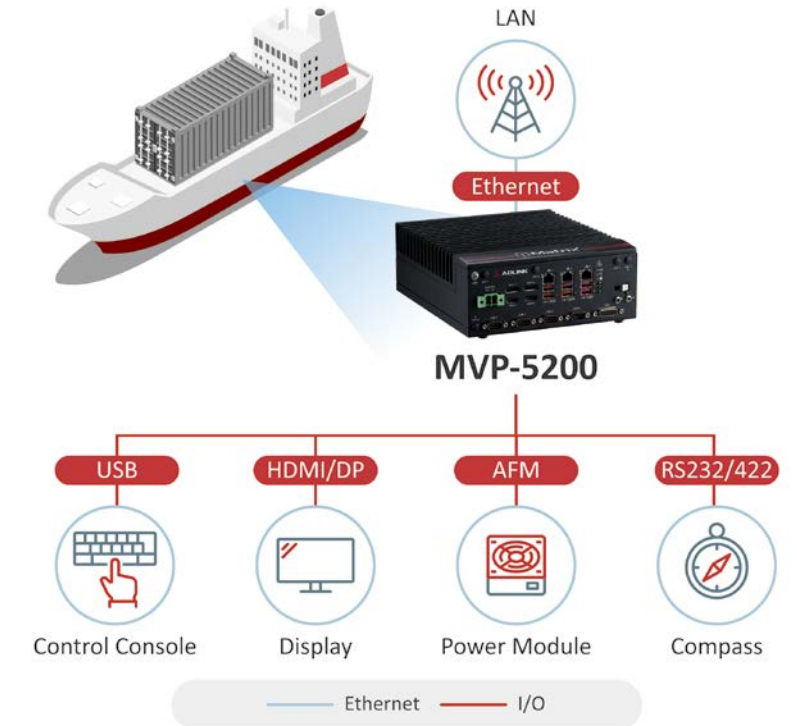
- MVP-5200 delivers high-performance rendering for ECDIS and radar, with stable AIS, radar, and GPS data integration
- Complies with IEC 60945 marine standards for certified reliability
- Fanless dual-slot design supports GPU and network cards for maintenance-free operation

Use Case

Maritime Navigation Control System

Overview

Accurate navigation requires systems that can process radar, GPS, AIS, and ECDIS data without interruption. Managing these inputs demands strong rendering performance and seamless integration to avoid delays or errors that could compromise safety. The MVP-5200 is designed for this environment, delivering high-performance rendering and seamless data integration in a compact, fanless platform. With marine-grade compliance and dual-slot flexibility for GPU and network expansion, it ensures reliable navigation control and long-term stability at sea.



Expandable Series



Model		MVP-3120	MVP-6200	MVP-6100	MXC-3340
System	CPU	Intel® Core™ 200S Series and 14/13/12th Gen Core™ Processors, up to 65W		9th Gen Intel® Core™ processors, up to 80W	Intel® Processor N-series & Atom X-series, up to 12W
	Chipset	Intel® H610E	Intel® R680E	Intel® C246 (optional: Intel® H310)	-
	Memory	DDR5 4800MHz, 2x SO-DIMM, up to 64GB	DDR5 3600 MHz, 4x SODIMM, up to 128GB (Support ECC memory)	DDR4 2400 MHz, 2x SODIMM, up to 32GB (Support ECC memory, only for Intel® chipset C246)	1x DDR5 4800MHz SO-DIMMs, up to 32G
	Storage	4x SATA for 2.5 drive (support RAID 0/1/5/10)	2x SATA for 2.5 drive (support RAID 0/1/5/10)	2x SATA for 2.5 drive (support RAID 0/1 only for Intel® chipset C246) 1x CFast type II	-
	OS	Windows® 10 IoT, Windows® 11 IoT, Ubuntu 22.04	Windows® 10 IoT LTSC or Ubuntu 22.04		Windows® 10/11 IoT Enterprise LTSC 21H2 (64bit) Ubuntu 22.04
	TPM	TPM 2.0 support			-
I/O Interfaces	Display	1x HDMI 1.4b 1x DP++ 1.4	2x HDMI 1.4b 2x DP++ 1.4	2x DP++ 1.2 1x DVI-D 1x VGA	2x DP 1x HDMI
	Serial Ports	-			2x isolated RS-232/422/485 DB9
	USB	4x USB 3.2 Gen1 (Type-A) 4x USB 2.0 (Type-A)	4x USB 3.2 Gen2 (Type-A) 2x USB 3.2 Gen1 (Type-A)	3x USB 3.1 Gen1 3x USB 2.0 1x USB 2.0 internal dongle (2x USB 3.1 up to Gen 2 with C246)	1x USB 3.2 Gen 2 3x USB 2.0
	Ethernet	1x 2.5GbE (Intel® i226) 2x 1.0GbE (Intel® i210) 1x 1.0GbE (Intel® i219)	3x 2.5GBE with TSN supported (i225) 1x vPro supported	2x 1.0GbE (Intel® i225) 1x 1.0GbE (Intel® i219) Support Intel® AMT/vPro™ with Intel® C246	4x GbE ports/I210IT
	COM	COM1/2: RS-232/422/485 COM3: RS-232	COM1/2: RS-232/422/485 COM3/4: RS-232	COM1/2: RS-232/422/485 COM3/4: RS-232 COM5/6: RS-232 (optional)	-
	DI/O	8 DI + 8 DO			
	Audio	Line-out, Mic-in			1x USB 3.2 Gen 2 + 3x USB 2.0
	SMA Antenna Connector	2	6		-
	CAN	-			2x DB9 isolated CAN ports
Extension Slots	USIM	-		2	-
	I2C	2 (3.3V/5V)			-
	Backplane Extension	1x PCIe 4.0 x16, 1x PCI x1	2 slots: 1x PCIe4.0 x16, 1x PCI x1 4 slots: 1x PCIe4.0x16, 2x PCIe3.0x4, 1x PCI		3x PCIe slots
	M.2	1x A+E Key 2230 1x M Key 2280	1x A+E Key 2230 1x B Key 3052/3042 1x M Key 2280		M.2 2280 M Key (PCIex2) M.2 2230 E Key with (Wi-Fi(PCIex1), BT(USB2.0)) M.2 3042 B-key (USB3.0/2.0) with SIM card
Power Supply	DC Input	12 to 24V, 280W adapter (optional)	9 to 32V, 280W adapter (optional)	12-24V (± 10% tolerance)	9V-36V DC input pluggable connectors with latch (GND, V-, V+)
	AC Input	280W AC/DC adapter (optional)		220 with 280W AC/DC adapter (optional)	100W external AC/DC adapter for AC input (optional)
Environmental	Operating Temperature	-20°C to 60°C (35W CPU) -20°C to 50°C (65W CPU)		-20°C to 60°C (35W CPU) -20°C to 50°C (65W CPU) -20°C to 40°C (80W CPU)	-15°C to 55°C (No air flow)

Integrated Series



Model		MVP-3100	MVP-5200	MVP-5100	MXC-3300
System	CPU	Intel® Core™ 200S Series and 14/13/12th Gen Core™ Processors, up to 65W		9th Gen Intel® Core™ processors, up to 65W	Intel® Processor N-series & Atom X-series, up to 12W
	Chipset	Intel® H610E	Intel® R680E	Intel® H310 (optional: Intel® C246)	-
	Memory	DDR5 4800MHz, 2x SO-DIMM, up to 64GB	DDR5 3600 MHz, 4x SODIMM, up to 128GB (Support ECC memory)	DDR4 2400 MHz, 2x SODIMM, up to 32GB (Support ECC memory, only for Intel® chipset C246)	1x DDR5 4800MHz SO-DIMMs, up to 32G
	Storage	2x SATA for 2.5 drive (support RAID 0/1/5/10)		2x SATA for 2.5 drive (support RAID 0/1 only for Intel® chipset C246) 1x CFast type II	-
	OS	Windows® 10 IoT, Windows® 11 IoT, Ubuntu 22.04	Windows® 10 IoT LTSC or Ubuntu 22.04		Windows® 10/11 IoT Enterprise LTSC 21H2 (64bit) Ubuntu 22.04
	TPM	TPM 2.0 support			-
I/O Interfaces	Display	1x HDMI 1.4b 1x DP++ 1.4	2x HDMI 1.4b 2x DP++ 1.4	2x DP++ 1.2 1x DVI-D 1x VGA	2x DP 1x HDMI
	Serial Ports	-			2x isolated RS-232/422/485 DB9
	USB	4x USB 3.2 Gen1 (Type-A) 4x USB 2.0 (Type-A)	6x USB 3.2 Gen2 (Type-A) 1x USB 2.0 internal dongle	3x USB 3.1 Gen1 3x USB 2.0 1x USB 2.0 internal dongle (2x USB 3.1 up to Gen 2 with C246)	1x USB 3.2 Gen 2 3x USB 2.0
	Ethernet	1x 2.5GbE (Intel® i226) 2x 1.0GbE (Intel® i210) 1x 1.0GbE (Intel® i219)	3x 2.5GbE (Intel® i225) support TSN	2x 1.0GbE (Intel® i225) 1x 1.0GbE (Intel® i219) Support Intel® AMT/vPro™ with Intel® C246	4x GbE ports/I210IT
	COM	COM1/2: RS-232/422/485 COM3: RS-232	COM1/2: RS-232/422/485 COM3/4: RS-232	COM1/2: RS-232/422/485 COM3/4: RS-232 COM5/6: RS-232 (optional)	-
	DI/O	8 DI + 8 DO			
	Audio	Line-out, Mic-in			1x USB 3.2 Gen 2 + 3x USB 2.0
	SMA Antenna Connector	2	6		-
	CAN	-			2x DB9 isolated CAN ports
Extension Slots	Mini PCIe	-	1x Full size (USB2.0, PCIe)		-
	USIM	-		2	-
	I2C	2 (3.3V/5V)			-
	M.2	1x A+E Key 2230 1x M Key 2280	1x B+M key 2280/3042		M.2 2280 M Key (PCIex2) M.2 2230 E Key with (Wi-Fi(PCIex1), BT(USB2.0)) M.2 3042 B-key (USB3.0/2.0) with SIM card
Power Supply	DC Input	12 to 24V, 280W adapter (optional)	9 to 32V, 280W adapter (optional)	12-24V (± 10% tolerance)	9V-36V DC input pluggable connectors with latch (GND, V-, V+)
	AC Input	280W AC/DC adapter (optional)		160W AC/DC adapter (optional)	100W external AC/DC adapter for AC input (optional)
Environmental	Operating Temperature	-20°C to 60°C (35W CPU) -20°C to 50°C (55W CPU)	-20°C to 60°C (35W CPU) -20°C to 50°C (65W CPU)		-15°C to 55°C (No air flow)

Compact Series



Model		MXE-310	MXE-230
System Core	Processor	Intel® Raptor Lake Processor i3/i5/i7 15/28W	Intel® Processor N-series & Atom X-series, up to 12W
	Core	6	4
	Base Freq	1.6 GHz	2 GHz
	MAX Turbo Freq.	4.5 GHz	3.6 GHz
	Memory	2x DDR5 SO-DIMMs, up to 4800MHz	1x 8G DDR5 SO-DIMMs, up to 32G
OS Support		Windows® 10/11 IoT Enterprise LTSC 21H2 (64bit) Ubuntu 22.04	
I/O Interfaces	Display	1x DP 1x HDMI (optional: 2x HDMI) 1x (Type-C)	1x DP 1x HDMI
	Ethernet	2x LAN (LAN1 Intel® i219IT LAN2 Intel® i225IT, support 2.5Gbps) 6x LAN (optional)	2x Gbe (Intel® i210IT, support 1Gbps/ 100Mbps/ 10Mbps) 4x GbE ports (Optional)
	Serial Ports	2x RS-232/422/485 DB9 connector 2x RS-232 DB9 connector	2x RS-232/422/485 DB9 Connector 4x RS-232/422/485 DB9 Connector (Optional)
	USB	3x USB 2.0 2x USB 3.2 1x USB4 (Type-C) 6x USB 3.2 Gen1 (Optional)	1x USB 3.2 Gen 2x1 ports (10Gbps) (Type-A) 3x USB 2.0 (Type-A) 7x USB 2.0 (optional)
	Audio	ALC888S, 1x line-in/ line-out, MIC-in	
	M.2	M.2 2280 M Key (PCIe x4) M.2 2230 E Key (PCIe x1, USB 2.0) M.2 3042 B-key (USB 3.0/2.0)	M.2 2280 M Key (PCIex2) M.2 2230 E Key with (Wi-Fi (PCIex1), BT(USB2.0)) M.2 3042 B-key (USB3.0/2.0) with SIM card
	DI/O	8-ch DI and 8-ch DO (optional)	Isolated 8x DI + 8x DO (optional)
	Expansion Slots	Yes (Function Board)	
Storage Devices	2.5 SATA	1x SATA III 6Gb/s for 2.5inch SSD	
Mechanical	M.2	M.2 2280 M Key (PCIex4)	M.2 2280 M Key (PCIex2)
Power Supply	DC Input	12-24V +-5%	
	AC Input	120W AC/DC adapter (optional)	
Environmental	Operating Temperature	-20°C to 60°C	

IIoT Gateways



Model		MXA-312M	MXA-200
System	CPU	Genio 520 MT8371, 2 ARM Cortex-A78 + 6 ARM Cortex-A55	NXP i.MX8M Plus with Quad core ARM Cortex-A53, 1.8GHz
	Memory	1 x LPDDR5(X), up to 6400MHz 16GB	LPDDR4 2GB/4GB 4000 MT/s
	Main storage	64GB UFS3.1 (onboard)	32GB/64GB eMMC (onboard)
	Sub storage	1 x Micro SD socket	
	TPM	TPM 2.0	
I/O Interfaces	RTC	Monthly difference max.180sec	
	USB	1 x USB 3.2 Gen 1 (Type-A) 1 x USB 2.0 (Type-A)	2x USB 3.0 (Type-A)
	Ethernet	2x GbE	
	COM	1 x RS-232 1 x RS-485 Terminal Connector	2x isolated RS-232/422/485 4-wire
	Display output	2 x HDMI (up to 4K@60fps)	1x HDMI up to 3840 x 2160 at 30Hz
Mechanical	M.2	M.2 2230 E Key with Wi-Fi (PCIex1), BT (USB2.0) M.2 3042 B-key with SIM card (USB2.0) (option by installed AFM board)	1x M.2 2230 E-key for WiFi/BT 1x M.2 2242 B-key (USB 3.0) for 5G or 4G/LTE
	Power supply	12V Terminal connector	12-24V DC
Environmental	Operating Temperature	-20°C to 70°C	

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